

# **Product Specification**

# 400GBASE-FR8 QSFP-DD Optical Transceiver Module FTCD1333E1PCL

#### PRODUCT FEATURES

- Hot-pluggable QSFP-DD Type 2 form factor
- Supports 425Gb/s aggregate bit rate
- Power dissipation < 13W
- RoHS-6 compliant
- Case temperature range of 0°C to +70°C
- Single 3.3V power supply
- Maximum link length of 2km on Single Mode Fiber (SMF)
- Aligned with IEEE 802.3bs
- 8x50G PAM4 DFB-based LAN-WDM transmitter
- 8x50G PAM4 retimed 400GAUI-8 electrical interface
- Duplex LC receptacles
- CMIS 3.0 Compliant
- I2C management interface



#### **APPLICATIONS**

• 400G FR8 applications with FEC

Finisar's FTCD1333E1PCL FR8 QSFP-DD transceiver modules are designed for use in 400 Gigabit Ethernet links on up to 10km of single mode fiber. They are compliant with the QSFP-DD MSA<sup>1</sup>, QSFP28 MSA<sup>2</sup>, IEEE P802.3bs and portions of IEEE P802.3bm. Digital diagnostic functions are available via the I2C interface, as specified by the MSA and Finisar Application Note AN-20xx<sup>5</sup>. The transceiver is RoHS-6 compliant per Directive 2011/65/EU4 and Finisar Application Note AN-2038<sup>4</sup>.

### PRODUCT SELECTION

# FTCD1333E1PCL

E: Ethernet protocol

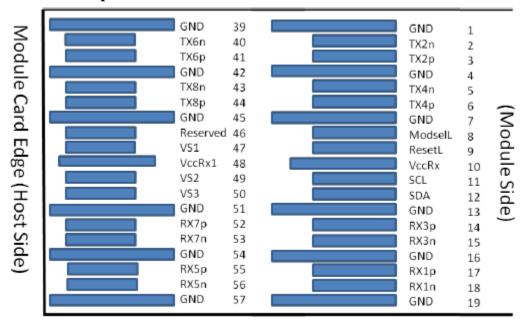
P: Pull-tab type release

C: Commercial temperature range

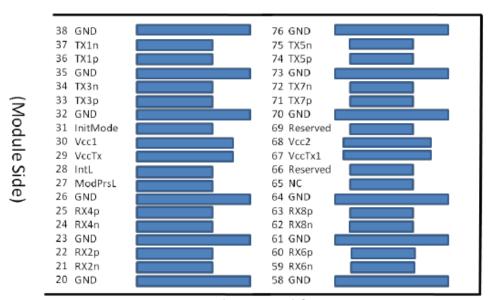
L: LC receptacles



# I. Pin Descriptions



Bottom side viewed from bottom



Top side viewed from top



Figure 1 – QSFP-DD -compliant 76-pin connector (per QSFP-DD MSA)

Pad	Logic	Symbol	Description	Plug	Notes
rau	Logic	Symbol	Description	Sequence <sup>4</sup>	Noces
1	1	GND	Ground	1B	1
2	CML-I	Tx2n	Transmitter Inverted Data Input	3B	-
3	CML-I	Tx2p	3B		
4	0.112 2	GND	Transmitter Non-Inverted Data Input Ground	1B	1
5	CML-I	Tx4n	Transmitter Inverted Data Input	3B	_
6	CML-I	Ти4р	Transmitter Non-Inverted Data Input	3B	
7	CML-1	GND	Ground	1B	,
	LVTTL-I	ModSelL	Module Select	3B	1
8					
9	LVTTL-I	ResetL VccRx	Module Reset	3B 2B	^
10	********		+3.3V Power Supply Receiver		2
11	LVCMOS-	SCL	2-wire serial interface clock	3B	
12	LVCMOS-	SDA	2-wire serial interface data	3B	
13	I/0	GND	Ground	1B	1
	CML-O			3B	1
14		Rx3p	Receiver Non-Inverted Data Output		
15	CML-0	Rx3n	Receiver Inverted Data Output	3B	_
16	C) (T) (C)	GND	Ground	1B	1
17	CML-0	Rxlp	Receiver Non-Inverted Data Output	3B	
18	CML-0	Rxln	Receiver Inverted Data Output	3B	
19		GND	Ground	1B	1
20		GND	Ground	1B 3B	1
21	CML-0		Rx2n Receiver Inverted Data Output		
22	CML-0	Rx2p	Receiver Non-Inverted Data Output	3B	
23		GND	Ground	1B	1
24	CML-0	Rx4n	Receiver Inverted Data Output	3B	
25	CML-0	Rx4p	Receiver Non-Inverted Data Output	3B	
26		GND	Ground	1B	1
27		ModPrsL	Module Present	3B	
28	LVTTL-O	IntL	Interrupt	3B	
29		VccTx +3.3V Power supply transmitter		2B	2
30		Vccl	+3.3V Power supply	2B	2
31	LVTTL-I	InitMode	Initialization mode; In legacy QSFP	3B	
			applications, the InitMode pad is called LPMODE		
32		GND	Ground	1B	1
33	CML-I	Ти3р	Transmitter Non-Inverted Data Input	3B	
34	CML-I	Tx3n	Transmitter Inverted Data Input	3B	
35	0.112 2	GND	Ground	1B	1
36	CML-I	Txlp	Transmitter Non-Inverted Data Input	3B	_
37	CML-I	Txln	Transmitter Non-Inverted Data Input Transmitter Inverted Data Input	3B	
	CHL-I				1
38		GND	Ground	1B	1
39		GND	Ground	1A	1
40	CML-I	Tx6n	Transmitter Inverted Data Input	3A	
41	CML-I	Тхбр	Transmitter Non-Inverted Data Input	3A	
42		GND	Ground	1A	1
43	CML-I	Tx8n	Transmitter Inverted Data Input	3A	
43	CHE				
44	CML-I	Тж8р	Transmitter Non-Inverted Data Input	3A	
			Transmitter Non-Inverted Data Input Ground	3A 1A	1
44		Tx8p	•		1 3
44 45		Tx8p GND	Ground	1A	_
44 45 46		Tx8p GND Reserved	Ground For future use Module Vendor Specific 1	1A 3A	3
44 45 46 47		Tx8p GND Reserved VS1	Ground For future use Module Vendor Specific 1 3.3V Power Supply	1A 3A 3A	3
44 45 46 47 48 49		Tx8p GND Reserved VS1 VccRx1	Ground For future use Module Vendor Specific 1 3.3V Power Supply Module Vendor Specific 2	1A 3A 3A 2A	3 3 2
44 45 46 47 48 49 50		Tx8p GND Reserved VS1 VccRx1 VS2 VS3	Ground For future use Module Vendor Specific 1 3.3V Power Supply Module Vendor Specific 2 Module Vendor Specific 3	1A 3A 3A 2A 3A 3A	3 3 2 3 3
44 45 46 47 48 49 50	CML-I	Tx8p GND Reserved VS1 VccRx1 VS2 VS3 GND	Ground For future use Module Vendor Specific 1 3.3V Power Supply Module Vendor Specific 2 Module Vendor Specific 3 Ground	1A 3A 3A 2A 3A 3A	3 3 2 3
44 45 46 47 48 49 50 51 52	CML-0	Tx8p GND Reserved VS1 VccRx1 VS2 VS3 GND Rx7p	Ground For future use Module Vendor Specific 1 3.3V Power Supply Module Vendor Specific 2 Module Vendor Specific 3 Ground Receiver Non-Inverted Data Output	1A 3A 3A 2A 3A 3A 1A 3A	3 3 2 3 3
44 45 46 47 48 49 50	CML-I	Tx8p GND Reserved VS1 VccRx1 VS2 VS3 GND	Ground For future use Module Vendor Specific 1 3.3V Power Supply Module Vendor Specific 2 Module Vendor Specific 3 Ground	1A 3A 3A 2A 3A 3A	3 3 2 3 3



			<u>-</u>			
56	CML-0	Rx5n	Receiver Inverted Data Output	3A		
57		GND	Ground	1A	1	
58		GND	Ground	1A	1	
59	CML-O	Rx6n	Receiver Inverted Data Output	3A		
60	CML-O	Rx6p	ceiver Non-Inverted Data Output 3A			
61		GND	round 1A 1			
62	CML-O	Rx8n	Receiver Inverted Data Output	3A		
63	CML-O	Rx8p	Receiver Non-Inverted Data Output	3A		
64		GND	Ground	1A	1	
65		NC	No Connect	3A	3	
66		Reserved	For future use	3A	3	
67		VccTxl	3.3V Power Supply	2A	2	
68		Vcc2	3.3V Power Supply	2A	2	
69		Reserved	For Future Use	3A	3	
70		GND	Ground	1A	1	
71	CML-I	Тх7р	Transmitter Non-Inverted Data Input 3A			
72	CML-I	Tx7n	Transmitter Inverted Data Input 3A			
73		GND	Ground 1A 1			
74	CML-I	Тх5р	Transmitter Non-Inverted Data Input	3A		
75	CML-I	Tx5n	Transmitter Inverted Data Input	3A		
76		GND	Ground 1A 1			
comm pote	on within ential unl on ground	the QSFP- ess otherw plane.	mmon ground (GND) for all signals and suppl DD module and all module voltages are refe ise noted. Connect these directly to the h	renced to t ost board s	his ignal-	
Require In I conn	irements able 4. ected wit d for a m	defined for VecRx, Vec thin the monaximum cur	Vccl, Vcc2, VccTx and VccTxl shall be appl or the host side of the Host Card Edge Conn Rxl, Vccl, Vcc2, VccTx and VccTxl may be indule in any combination. The connector Vcc crent of 1000 mA.	ector are l nternally pins are e	listed	
Note 3: All Vendor Specific, Reserved and No Connect pins may be terminated with 50 ohms to ground on the host. Pad 65 (No Connect) shall be left unconnected within the module. Vendor specific and Reserved pads shall have an impedance to GND that is greater than 10 kOhms and less than 100 pF.						
modu Cont	le. The s act seque ence 1A,	equence is ence A will	specifies the mating sequence of the host of IA, 2A, 3A, 1B, 2B, 3B. (see Figure 2 for make, then break contact with additional sen occur simultaneously, followed by 2A, 2	pad locati QSFP-DD pac	ions)	

# **II.** Absolute Maximum Ratings

Module performance is not guaranteed beyond the operating range (see Section VI). Exceeding the limits below may damage the transceiver module permanently.

Parameter	Symbol	Min	Тур	Max	Unit	Ref.
Maximum Supply Voltage	Vcc	-0.5		4.0	V	
Storage Temperature	$T_{S}$	-40		+85	°C	
Case Operating Temperature	$T_{OP}$	0		+70	°C	
Relative Humidity	RH	15		85	%	1
Receiver Damage Threshold, per Lane	$P_{Rdmg}$	6.3			dBm	

### Notes:

1. Non-condensing.



# III. Electrical Characteristics (EOL, $T_{OP} = 0$ to +70 °C, $V_{CC} = 3.135$ to 3.465 Volts)

Parameter	Symbol	Min	Тур	Max	Unit	Ref.
Supply Voltage	Vcc	3.135	3.3	3.465	V	
Supply Current	Icc			3.83	A	
Module total power	P			13	W	1
Transmitter						
Signaling rate per lane		26.5	625± 100 p	pm.	Gbd	
Differential data input voltage per lane	Vin,pp,diff	900			mV	2
Differential input return loss			quation (83) EEE802.3br		dB	
Differential to common mode input return loss			quation (83) EEE802.3br		dB	
Differential termination mismatch				10	%	
Module stress input test			er 120E.3.4. EEE802.3bs			3
Single-ended voltage tolerance range		-0.4		3.3	V	
DC common mode voltage		-350		2850	mV	4
Receiver						
Signaling rate per lane		26.5	625± 100 p	pm.	Gbd	
AC common-mode output voltage (RMS)				17.5	mV	
Differential output voltage				900	mV	
Near-end ESMW (Eye symmetry mask width)		0.265			UI	
Near-end Eye height, differential (min)		70			mV	
Far-end ESMW (Eye symmetry mask width)		0.2			UI	
Far-end Eye height, differential (min)		30			mV	
Far-end pre-cursor ISI ratio		-4.5		2.5	dB	
Differential output return loss			equation 83 EEE802.3br			
Common to differential mode			equation 83			
conversion return loss		II	EEE802.3br			
Differential termination mismatch				10	%	
Transition time (min, 20% to 80%)		9.5			ps	
DC common mode voltage (min)		-350		2850	mV	4

#### Notes:

- 1. Maximum total power value is specified across the full temperature and voltage range.
- 2. With the exception to 120E.3.1.2 that the pattern is PRBS31Q or scrambled idle.
- 3. Meets specified BER
- 4. DC common mode voltage generated by the host. Specification includes effects of ground offset voltage.



# IV. Optical Characteristics (EOL, $T_{OP} = 0$ to +70 °C, $V_{CC} = 3.135$ to 3.465 Volts)

Meets 400GBASE-FR8 as being defined by IEEE P802.3bs

Parameter	Symbol	Min	Тур	Max	Unit	Ref.
Transmitter						
Signaling rate (each lane (range)		26	$6.5625 \pm 100$	ppm	GBd	
Modulation format			PAM4			
Lane wavelengths (range)		12 12 12 12 12 13	272.55 to 127 276.89 to 127 281.25 to 128 285.65 to 128 294.53 to 129 299.02 to 130 303.54 to 130 308.09 to 131	78.89 63.27 67.68 66.59 01.09 05.63	nm	
Side-mode suppression ratio (SMSR)		30	008.09 to 131	.0.19	dB	
Total average launch power		30		13.2	dBm	
Average launch power, each lane				5.3	dBm	1
Average launch power, each lane		-3.5			dBm	2
Outer Optical Modulation Amplitude (OMAouter), each lane		-0.5		5.5	dBm	3
Difference in launch power between any two lanes (OMAouter)				4	dB	
Launch power in OMAouter minus TDECQ, each lane		-1.8			dBm	
Transmitter and dispersion eye closure for PAM4 (TDECQ), each lane				3.1	dB	
Average launch power of OFF transmitter, each lane				-30	dBm	
Extinction ratio		3.5			dB	
RIN <sub>16.5</sub> OMA				-132	dB/Hz	
Optical return loss tolerance				16.5	dB	
Transmitter reflectance				-26	dB	4

#### Notes:

- 1. As the total average launch power limit has to be met, not all of the lanes can operate at the maximum average launch power, each lane.
- 2. Average launch power, each lane (min) is informative and not the principal indicator of signal strength. A transmitter with launch power below this value cannot be compliant; however, a value above this does not ensure compliance.
- 3. Even if the TDECQ < 1 dB, the OMAouter (min) must exceed this value
- 4. Transmitter reflectance is defined looking into the transmitter



Parameter	Symbol	Min	Тур	Max	Unit	Ref.
Receiver						
Signaling rate (each lane (range)		26.5625 ± 100 ppm			GBd	
Modulation format			PAM4			
Lane wavelengths (range)	1272.55 to 1274.54 1276.89 to 1278.89 1281.25 to 1283.27 1285.65 to 1287.68 1294.53 to 1296.59 1299.02 to 1301.09 1303.54 to 1305.63 1308.09 to 1310.19		nm			
Damage threshold, each lane		6.3			dBm	1
Average receive power, each lane				5.3	dBm	
Average receive power, each lane		-7.5			dBm	2
Receive power (OMAouter), each lane				5.7	dBm	
Difference in receive power between any two lanes (OMAouter)				4.1	dBm	
Receiver reflectance				-26	dB	
Receiver sensitivity (OMAouter), each lane				-5.3	dBm	3
Stressed receiver sensitivity (OMAouter), each lane				-3.1	dBm	4
Conditions of stressed receiver sensitivit	y test:					
Stressed eye closure for PAM4 (SECQ), lane under test		3.1		dB	5	
OMAouter of each aggressor lane			1		dBm	

### Notes:

- 1. The receiver shall be able to tolerate, without damage, continuous exposure to an optical input signal having this average power level.
- 2. Average receive power, each lane (min) is informative and not the principal indicator of signal strength. A received power below this value cannot be compliant; however, a value above this does not ensure compliance.
- 3. Receiver sensitivity (OMAouter), each lane (max) is informative and is defined for a transmitter with SECQ of 0.9 dB.
- 4. Measured with conformance test signal at TP3 (see 122.8.9) for the BER specified in 122.1.1.
- 5. These test conditions are for measuring stressed receiver sensitivity. They are not characteristics of the receiver.

## V. General Specifications

Parameter	Symbol	Min	Тур	Max	Units	Ref.
Bit Rate (all wavelengths combined)	BR			425	Gb/s	1
Bit Error Ratio	BER			2.4x10 <sup>-4</sup>		2
Maximum Supported Distances						
Fiber Type						
SMF per G.652	Lmax1			2	km	

#### Notes:

- 1. Supports 400GBASE-FR8 per IEEE P802.3bs.
- 2. As defined by IEEE P802.3bs.



# VI. Environmental Specifications

Finisar FTCD1333E1PCL FR8 QSFP-DD transceivers have an operating case temperature range of 0°C to +70°C.

Parameter	Symbol	Min	Тур	Max	Units	Ref.
Case Operating Temperature	$T_{op}$	0		+70	°C	
Storage Temperature	$T_{sto}$	-40		+85	°C	

## VII. Regulatory Compliance

Finisar FTCD1333E1PCL FR8 QSFP-DD transceivers are Class 1 Laser Products. They are certified per the following standards:

Feature	Agency	Standard
Laser Eye Safety	FDA/CDRH	CDRH 21 CFR 1040 and Laser Notice 50
Laser Eye	TÜV	EN 60825-1: 2007
Safety	10 V	IEC 60825-2: 2004+A1+A2
Electrical	TÜV	EN 60950
Safety	10 V	EN 00930
Electrical	UL/CSA	CLASS 3862.07
Safety		CLASS 3862.87

Copies of the referenced certificates are available at Finisar Corporation upon request.

## **III.** Digital Diagnostics Functions

FTCD1333E1PCL FR8 QSFP-DD transceivers support the I2C-based diagnostics interface specified by the SFF Commitee<sup>1</sup>. See also Finisar Application Note AN-20xx (TBD).

### **IX.** Memory Contents

Per QSFP-DD MSA Specification<sup>1</sup>. See Finisar Application Note AN-20xx (TBD).



# **XI.** Mechanical Specifications

Finisar FTCD1333E1PCL FR8 QSFP-DD transceivers are compatible with the QSFP-DD Type 2 Specification for pluggable form factor modules.

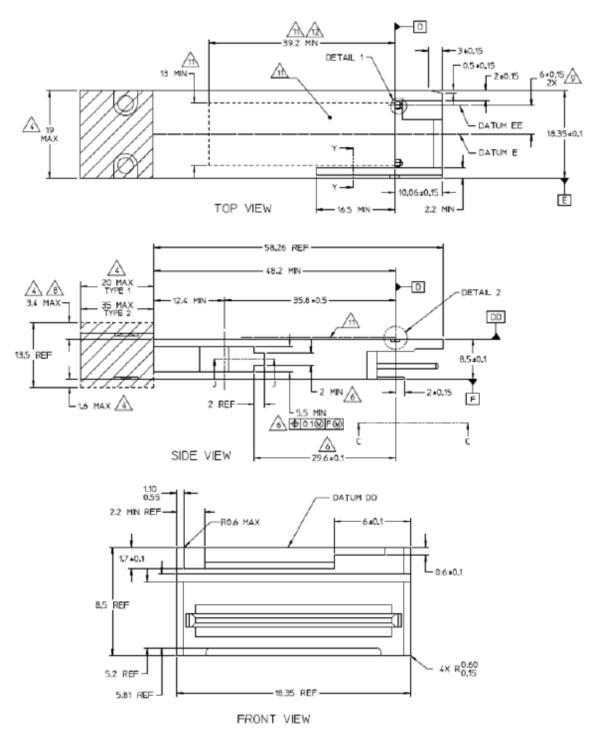


Figure 2. FTCD1333E1PCL Mechanical Dimensions.





Figure 3. Product Label

#### XII. References

- 1. QSFP-DD Specification for QSFP Double Density 8X Pluggable Transceiver
- 2. SFF-8665: "QSFP+ 28Gb/s 4X Pluggable Transceiver Solution (QSFP28)", Rev 1.9, June 29, 2015 and associated SFF documents referenced therein:
  - i. SFF-8661
  - ii. SFF-8679
  - iii. SFF-8636
  - iv. SFF-8662
  - v. SFF-8663
  - vi. SFF-8672
  - vii. SFF-8683
- 3. Directive 2011/65/EU of the European Parliament and of the Council, "on the restriction of the use of certain hazardous substances in electrical and electronic equipment," July 1, 2011.
- 4. "Application Note AN-2038: Finisar Implementation Of RoHS Compliant Transceivers", Finisar Corporation, January 21, 2005.
- 5. Application Note AN-2153, Initialization, Finisar Corporation.
- 6. Application Note AN-2154, EEPROM Map, Finisar Corporation.

#### **For More Information:**

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